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Cover Letter – FMS2

Machine Sensor Art No 584 91 89 05

This cover letter is to clarify difference and similarities in-between HW and SW changes used during the certification process and during production of the sensor.

With this letter Husqvarna AB guarantees that no changes of components on the PCBA nor changes in SW versions that affects the BLE functionality nor RF performance have been made.

| HW - revision | Comments |
|----------------------------|---|
| P1.2 A Prototype, not sold | PCBA used during certification |
| P1.2 B Prototype, not sold | Updated SoC with more RAM compared to P1.2 A. |
| | PCBA used during certification |
| R1.0 A Released | Identical to P1.2 B except: Color on PCB is blue. Some |
| | via holes are not covered by coating. |
| R1.1 A Released | Identical to P1.2 B except for the color on the PCB that is |
| | blue instead of green |
| R1.2 A Released | Identical to R1.1 but the two bigger holes on the PCB are covered to facilitate automatic machine coating of the board. See red X on photo. |

| SW - revision | Comments |
|---------------|--|
| DTM V1.1 | Software created by Silicon Labs, provided for the |
| | validation of a Bluetooth low energy device's radio- |
| | frequency (RF) physical layer (PHY), so as to ultimately |
| | guarantee an end product's interoperability and |
| | performance quality. Used on HW P1.2 A |
| DTM V2.0 | Same as DTM V1.1 but for HW P1.2 B |
| 0.2.22.60 | Software version used for BLE profile testing. |
| 2.4 | SILAB Bluetooth Stack SW used in all HW versions |